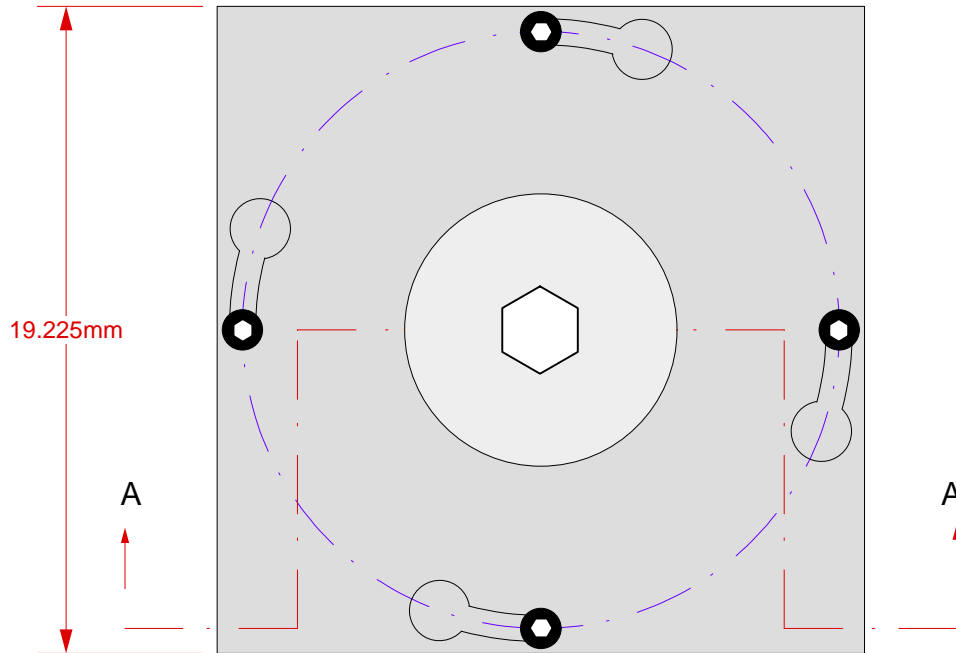


Top View

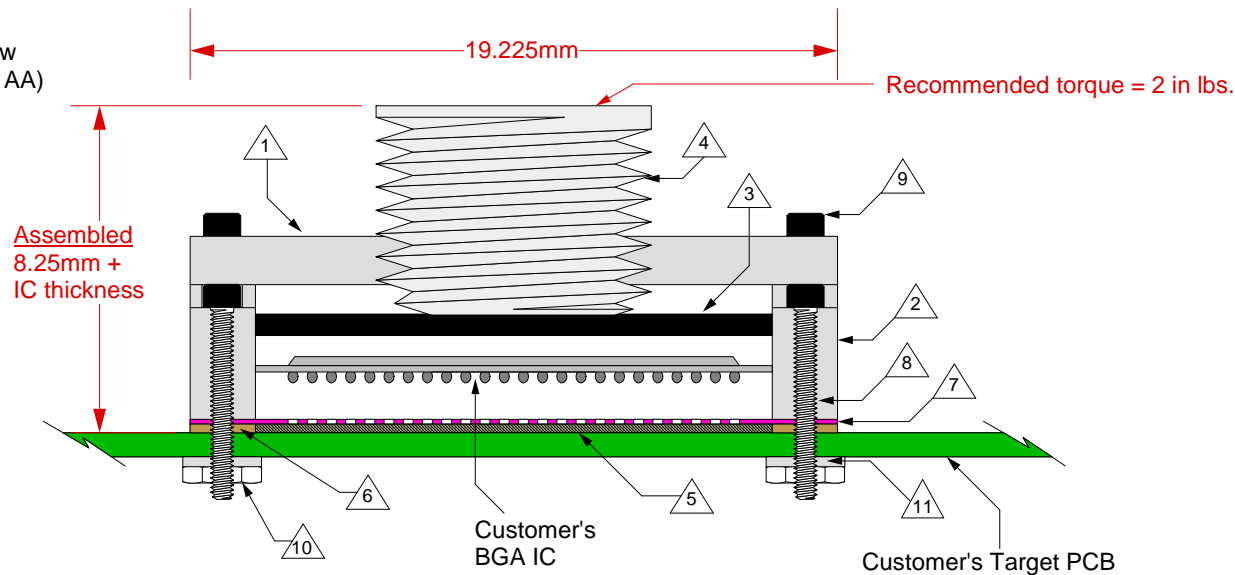


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



- 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum.
Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with
black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD
0.64mm thickness.

SG-BGA-6003 Drawing

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www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: G

Drawing: Meghann Fedde

Date: 8/15/01

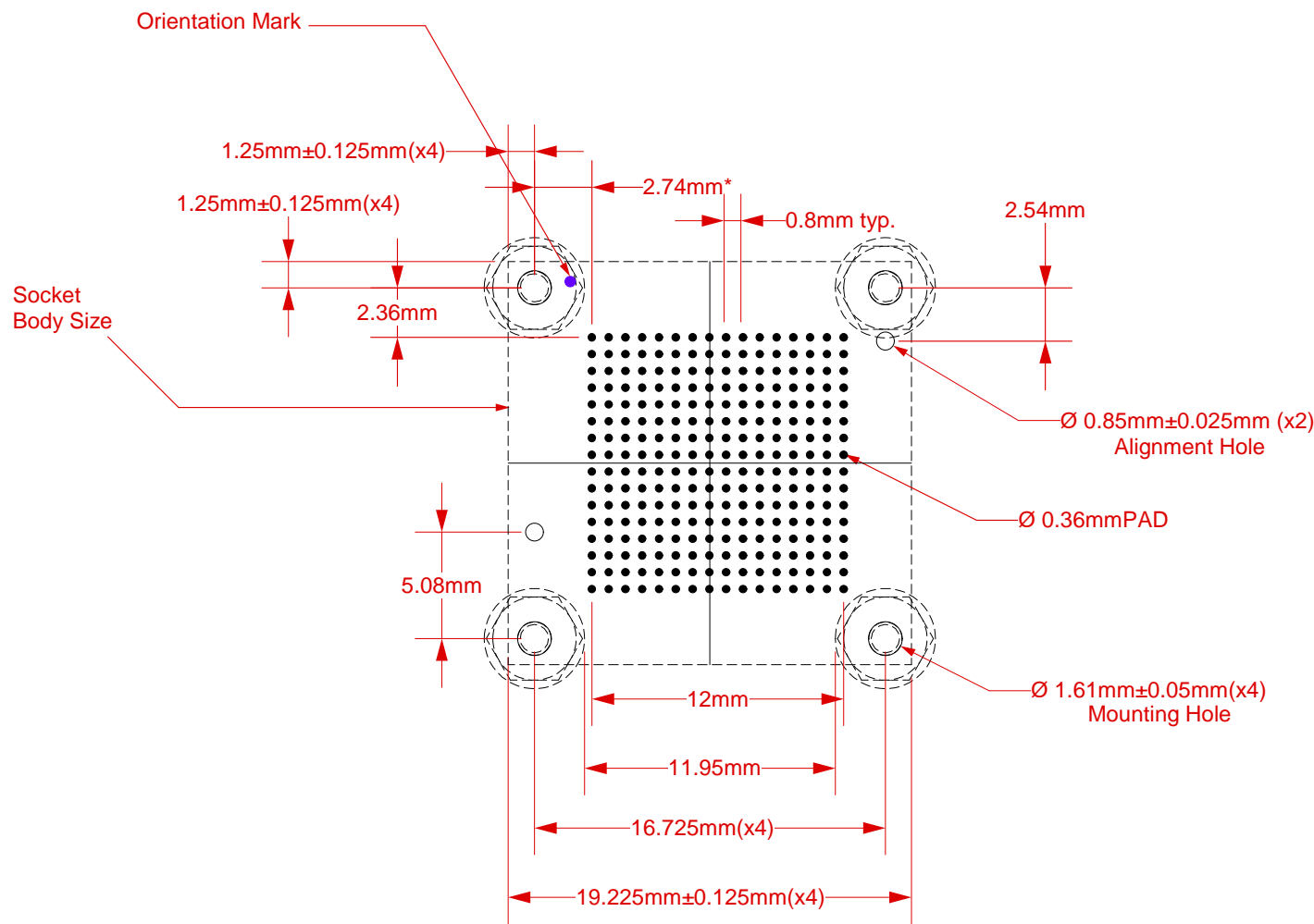
File: SG-BGA-6003 Dwg.mcd

Modified: 6/2/09

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

PAGE 1 of 3


***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

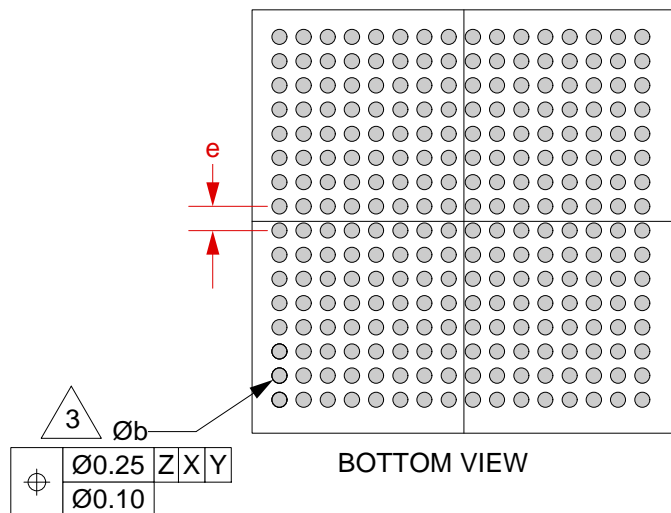
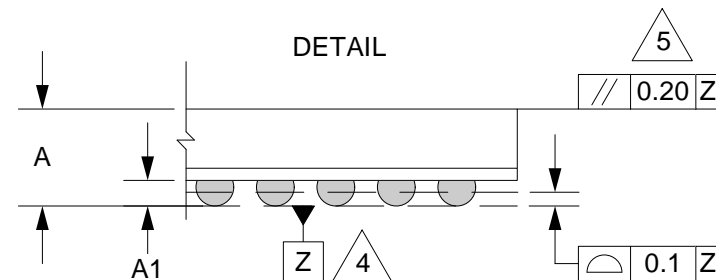
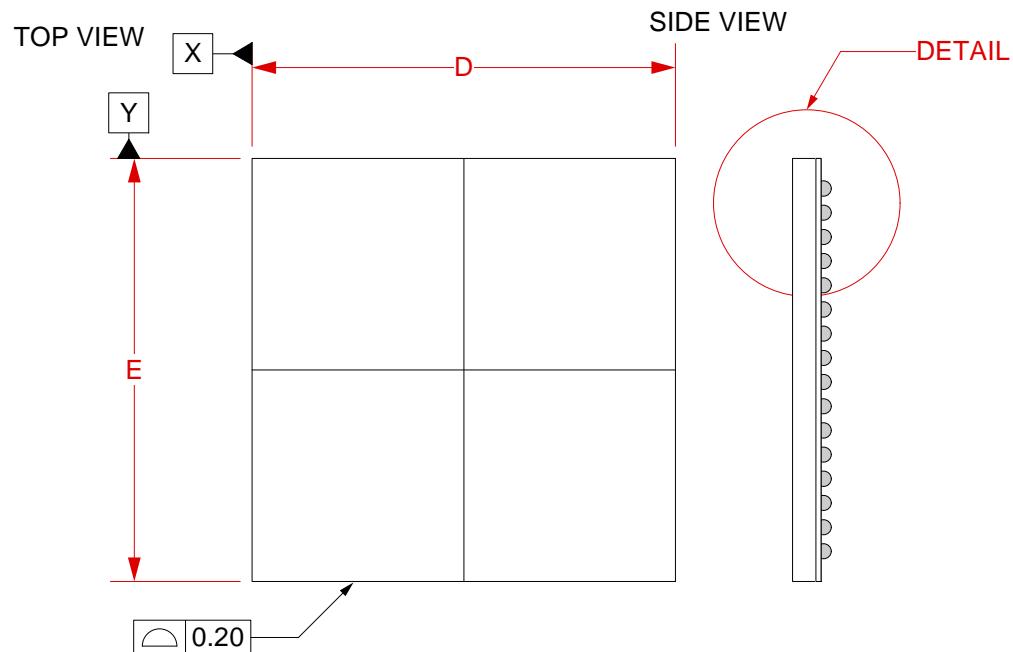


Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

	SG-BGA-6003 Drawing		Status: Released	Scale: 3:1	Rev: G
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			File: SG-BGA-6003 Dwg.mcd		Modified: 6/2/09



- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.2	0.34
b		0.45
D	14.00 BSC	
E	14.00 BSC	
e	0.80 BSC	

Array 16x16

SG-BGA-6003 Drawing

Status: Released

Scale: -

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